

ABSTRACT OF THE DISCLOSURE

A method including forming a chemically soluble coating on a plurality exposed contacts on a surface of a circuit substrate; scribing the surface of the substrate along scribe areas; and after scribing, removing a portion of the coating. A method including forming a circuit structure comprises a plurality of exposed contacts on a surface, a location of the exposed contacts defined by a plurality of scribe streets; forming a coating comprising a chemically soluble material on the exposed contacts; scribing the surface of the substrate along the scribe streets; and after scribing, removing the coating. A method including coating a surface of a circuit substrate comprising a plurality of exposed contacts with a chemically soluble material; scribing the surface of the substrate along scribe areas; removing the coating; and sawing the substrate in the scribe areas.